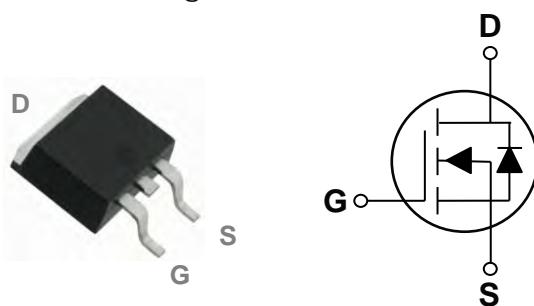


20V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO-252 Pin Configuration



BVDSS	RDS(ON)	ID
20V	17mΩ	30A

Features

- 20V,30A, RDS(ON) =17mΩ @VGS = 4.5V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings T_c=25 °C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{Gs}	Gate-Source Voltage	±16	V
I _D	Drain Current – Continuous (Chip Limitation ,T _c =25 °C)	30	A
	Drain Current – Continuous (Chip Limitation ,T _c =100 °C)	19	A
I _{DM}	Drain Current – Pulsed ¹	120	A
P _D	Power Dissipation (T _c =25 °C)	24.9	W
	Power Dissipation – Derate above 25 °C	0.20	W/°C
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	5.02	°C/W



FTK2612AD

20V N-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Static State Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.015	----	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 16\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	14	17	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_D=5\text{A}$	---	18.5	24	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.5	0.8	1.2	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-2.76	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=5\text{A}$	---	14	---	S

Dynamic Characteristics

Q_g	Total Gate Charge	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=5\text{A}$	---	5.9	12	nC
Q_{gs}	Gate-Source Charge		---	0.7	2	
Q_{gd}	Gate-Drain Charge		---	1.8	4	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_G=3.3\Omega$ $I_D=1\text{A}$	---	4.8	10	ns
T_r	Rise Time		---	7.5	15	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	16.5	32	
T_f	Fall Time		---	4.8	10	
C_{iss}	Input Capacitance	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	775	1440	pF
C_{oss}	Output Capacitance		---	95	190	
C_{rss}	Reverse Transfer Capacitance		---	58	120	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	2.2	---	Ω

Drain - Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	30	A
I_{SM}	Pulsed Source Current ²		---	---	60	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

20V N-Channel MOSFETs

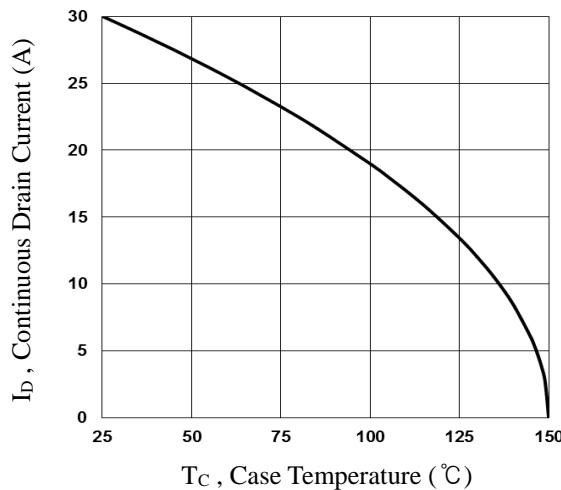


Fig.1 Continuous Drain Current vs. T_C

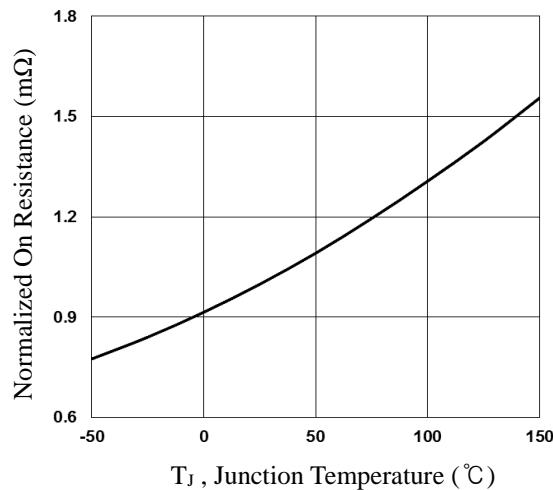


Fig.2 Normalized RDS(on) vs. T_J

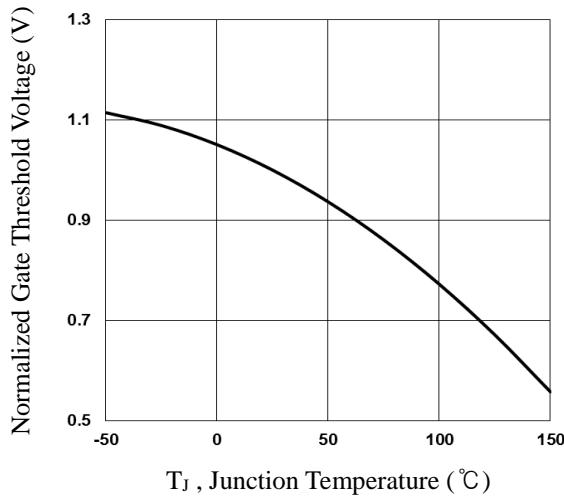


Fig.3 Normalized V_{th} vs. T_J

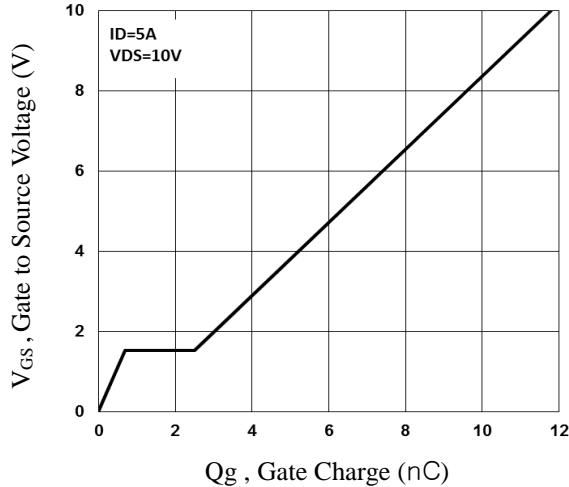


Fig.4 Gate Charge Waveform

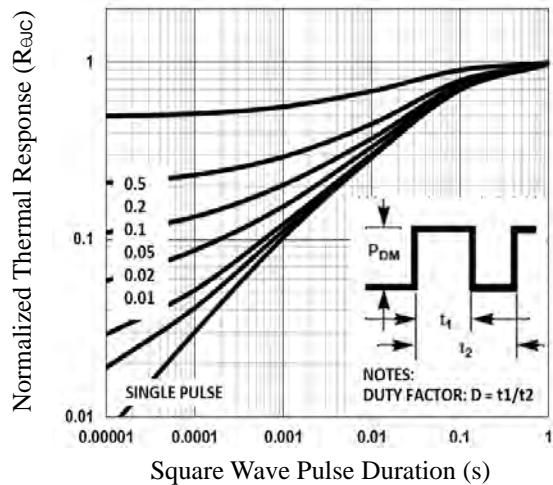


Fig.5 Normalized Transient Impedance

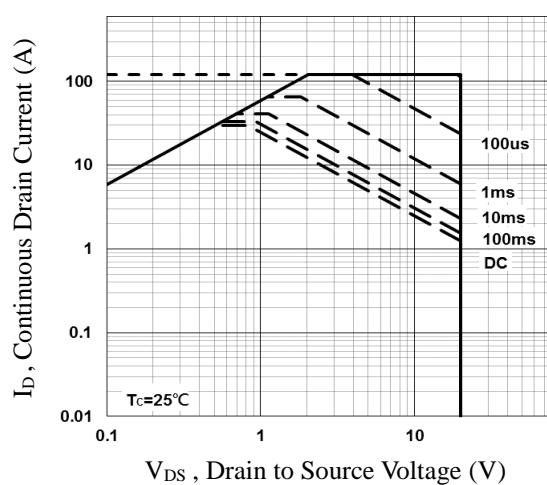


Fig.6 Maximum Safe Operation Area

20V N-Channel MOSFETs

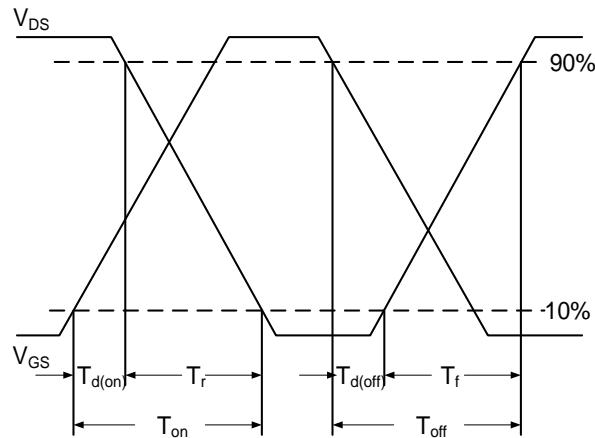


Fig.7 Switching Time Waveform

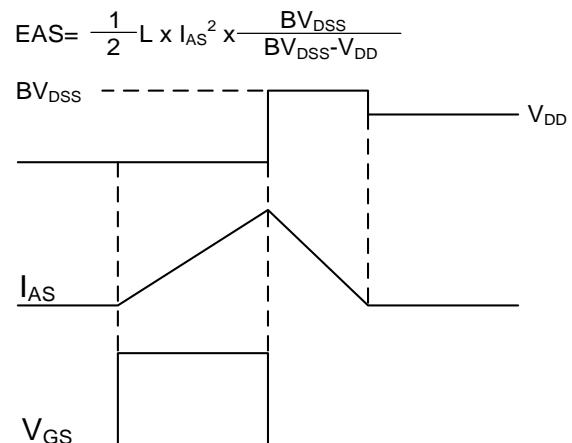
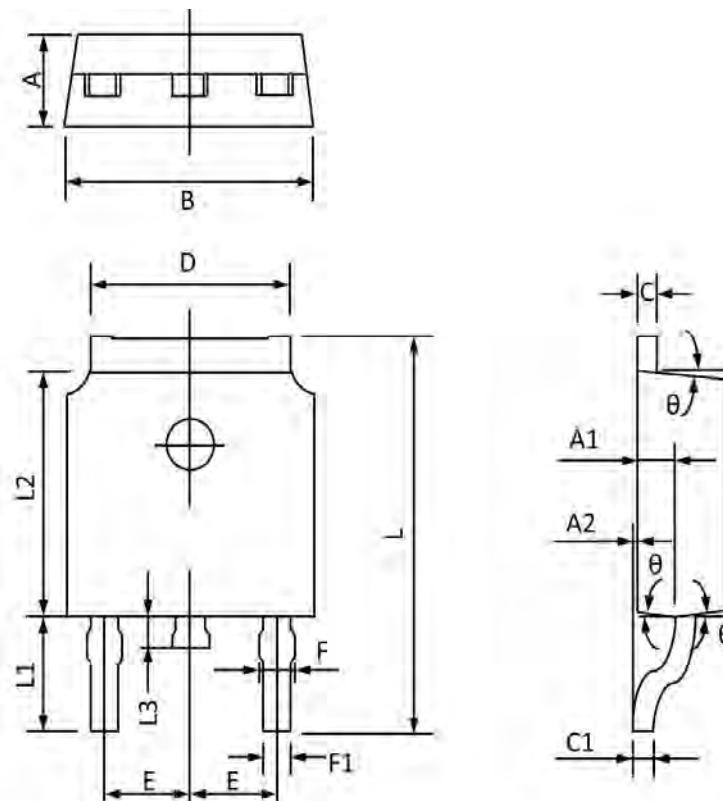


Fig.8 EAS Waveform

20V N-Channel MOSFETs

TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°